

HEXFRED® Ultrafast Diodes, 300 A (INT-A-PAK Power Modules)



INT-A-PAK

PRODUCT SUMMARY						
V _R	1200 V					
V _F (typical) at 300 A at 25 °C	2.18 V					
t _{rr} (typical) at 45 A	233 ns					
I _{F(DC)} at T _C	300 A at 60 °C					
Package	INT-A-PAK					
Circuit	Single diode					

FEATURES

· Electrically isolated: DCB base plate



• Standard JEDEC® package

· Simplified mechanical designs, rapid assembly

COMPLIAN

- High surge capability
- · Large creepage distances
- Case style INT-A-PAK
- · Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

REMARKS

- Product reliability results valid for $T_J = 150~^{\circ}C$
- Recommended operation temperature T_{op} = 150 °C

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Cathode to anode voltage	V_R		1200	V		
Continuous forward current	_	T _C = 25 °C	375	А		
	IF	T _C = 60 °C	300			
Single pulse forward current	I _{FSM}	T _J = 25 °C	2400			
Maximum power dissipation	В	T _C = 25 °C	1040	W		
	P _D	T _C = 60 °C	750			
RMS isolation voltage	V _{ISOL}	50 Hz, circuit to base, all terminal shorted, t = 1 s	3500	V		
Junction temperature range	TJ		-40 to +150	°C		
Storage temperature range	T _{Stg}		-40 to +150			

ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Cathode to anode breakdown voltage	V_{BR}	I _R = 500 μA	1200	-	-		
Maximum forward voltage	V_{FM}	I _F = 300 A	-	2.18	2.23	V	
		$I_F = 300 \text{ A}, T_J = 150 \text{ °C}$	-	2.24	2.47		
Maximum reverse leakage current	I _{RM}	V _R = 1200 V	-	0.06	0.2	mA	
		$T_J = 150 ^{\circ}\text{C}, V_R = 1200 \text{V}$	-	-	20		



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Diode reverse recovery charge	Q _{rr}	T _J = 25 °C	$I_F = 45 \text{ A}$ $V_R = 400 \text{ V}$ $dI_F/dt = 500 \text{ A/}\mu\text{s}$	-	3.5	-	μC
		T _J = 125 °C		-	10.4	-	
Reverse recovery time	t _{rr}	T _J = 25 °C		-	233	-	ns
		T _J = 125 °C		-	396	-	
Reverse recovery current	I _{rr}	T _J = 25 °C		-	30	-	А
		T _J = 125 °C		-	53	-	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Maximum internal thermal resistance, junction to case per leg		R_{thJC}	DC operation 0.12		°C/W		
Typical thermal resistance, case to heatsink per module		R _{thCS}	Mounting surface flat, smooth and greased	0.05	C/VV		
Mounting torque ± 10 %	to heatsink		A mounting compound is recommended and the torque should be rechecked after a period of 3 hours	4	Nm		
	busbar		to allow for the spread of the compound.	6	INIII		
Approximate weight				200	g		
				7.1	oz.		
Case style				New INT	-A-PAK		

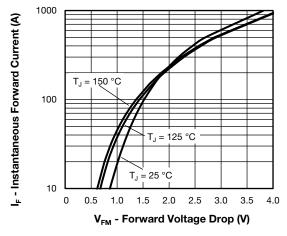


Fig. 1 - Typical Forward Voltage Drop Characteristics

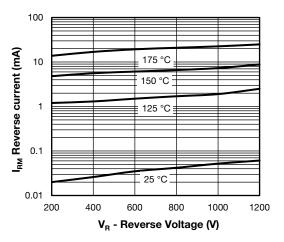


Fig. 2 - Typical Value of Reverse Current vs. Reverse Voltage

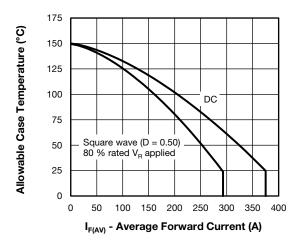


Fig. 3 - Maximum Allowable Case Temperature vs. Average Forward Current

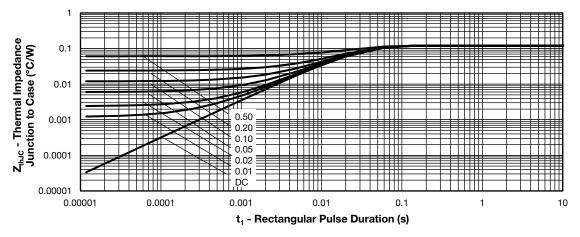


Fig. 4 - Maximum Thermal Impedance RthJC Characteristics

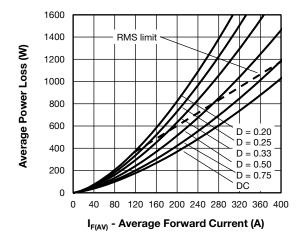


Fig. 5 - Forward Power Loss Characteristics

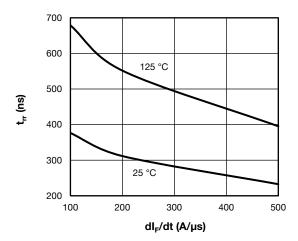
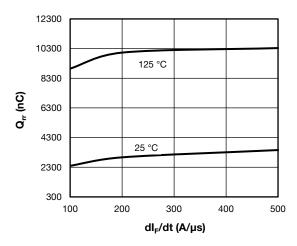


Fig. 6 - Typical Reverse Recovery Time vs. dI_F/dt





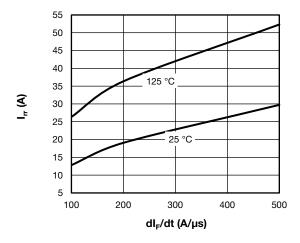
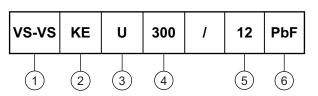


Fig. 8 - Typical Reverse Recovery Current vs. dl_F/dt

ORDERING INFORMATION TABLE

Device code



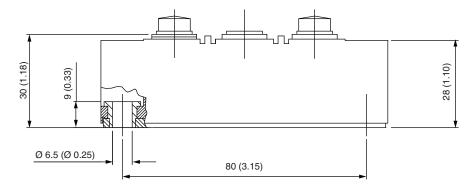
- 1 Vishay Semiconductors product
- KE = circuit configuration
- U = ultrafast diode
- 4 Current rating 300 = 300 A
- Voltage rating (12 = 1200 V)
- 6 PbF = lead (Pb)-free

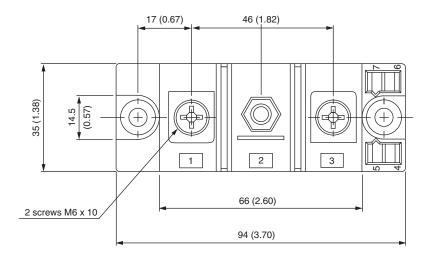
CIRCUIT CONFIGURATION

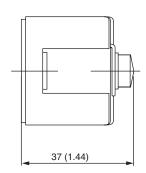




DIMENSIONS in (inches) millimeters **INT-A-PAK DBC**









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Vishay

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